BOURNS®

- 12 A Continuous On-State Current
- 100 A Surge-Current
- Glass Passivated Wafer
- 400 V to 800 V Off-State Voltage
- Max I_{GT} of 20 mA

This series is obsolete and not recommended for new designs.

Pin 2 is in electrical contact with the mounting base.

MDC1ACA

absolute maximum ratings over operating case temperature (unless otherwise noted)

RATING		SYMBOL	VALUE	UNIT	
	TIC126D		400		
Repetitive peak off-state voltage	TIC126M	V	600	V	
	TIC126S	V_{DRM}	700		
	TIC126N		800		
Repetitive peak reverse voltage	TIC126D		400	V	
	TIC126M	V	600		
	TIC126S	V _{RRM}	700		
	TIC126N		800		
Continuous on-state current at (or below) 70°C case temperature (see Note 1)		I _{T(RMS)}	12	Α	
Average on-state current (180° conduction angle) at (or below) 70°C case temperature		I _{T(AV)}	7.5	Α	
(see Note 2)			7.5		
Surge on-state current at (or below) 25°C case temperature (see Note 3)		I _{TM}	100	Α	
Peak positive gate current (pulse width ≤ 300 μs)		I _{GM}	3	Α	
Peak gate power dissipation (pulse width ≤ 300 μs)		P_{GM}	5	W	
Average gate power dissipation (see Note 4)		$P_{G(AV)}$	1	W	
Operating case temperature range		T _C	-40 to +110	°C	
Storage temperature range		T _{stg}	-40 to +125	°C	
Lead temperature 1.6 mm from case for 10 seconds		T _L	230	°C	

- NOTES: 1. These values apply for continuous dc operation with resistive load. Above 70°C derate linearly to zero at 110°C.
 - 2. This value may be applied continuously under single phase 50 Hz half-sine-wave operation with resistive load. Above 70°C derate linearly to zero at 110°C.
 - 3. This value applies for one 50 Hz half-sine-wave when the device is operating at (or below) the rated value of peak reverse voltage and on-state current. Surge may be repeated after the device has returned to original thermal equilibrium.
 - 4. This value applies for a maximum averaging time of 20 ms.

PRODUCT INFORMATION



electrical characteristics at 25°C case temperature (unless otherwise noted)

	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT	
I _{DRM}	Repetitive peak off-state current	V _D = rated V _{DRM}		T _C = 110°C			2	mA
I _{RRM}	Repetitive peak reverse current	V _R = rated V _{RRM}	I _G = 0	T _C = 110°C			2	mA
I _{GT}	Gate trigger current	V _{AA} = 12 V	$R_L = 100 \Omega$	t _{p(g)} ≥ 20 μs		8	20	mA
		$V_{AA} = 12 \text{ V}$ $t_{p(g)} \ge 20 \mu\text{s}$	$R_L = 100 \Omega$	T _C = - 40°C			2.5	
V _{GT} Gate trigger voltage	Gate trigger voltage	$V_{AA} = 12 \text{ V}$ $t_{p(g)} \ge 20 \mu\text{s}$	$R_L = 100 \Omega$			0.8	1.5	٧
		$V_{AA} = 12 \text{ V}$ $t_{p(g)} \ge 20 \mu\text{s}$	$R_L = 100 \Omega$	T _C = 110°C	0.2			
I _H	Holding current	V _{AA} = 12 V Initiating I _T = 100 mA		T _C = - 40°C			100	mA
IH HOMING	. returning content	$V_{AA} = 12 \text{ V}$ Initiating $I_T = 100 \text{ mA}$					40	
V _T	On-state voltage	I _T = 12 A	(see Note 5)				1.4	V
dv/dt	Critical rate of rise of off-state voltage	V _D = rated V _D	I _G = 0	T _C = 110°C		400		V/µs

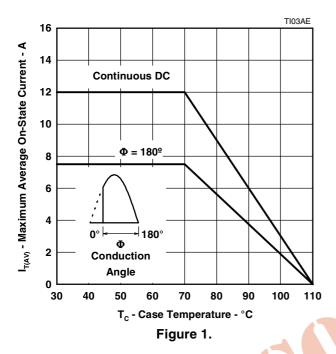
NOTE 5: This parameter must be measured using pulse techniques, t_p = 300 µs, duty cycle ≤ 2 %. Voltage sensing-contacts, separate from the current carrying contacts, are located within 3.2 mm from the device body.

thermal characteristics

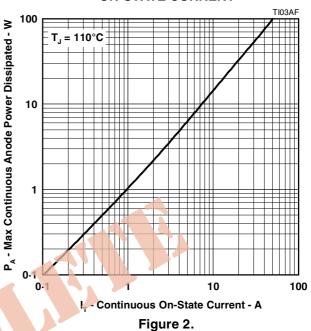
PARAMETER	MIN	TYP	MAX	UNIT
R _{BJC} Junction to case thermal resistance			2.4	°C/W
R _{0JA} Junction to free air thermal resistance			62.5	°C/W

THERMAL INFORMATION

AVERAGE ON-STATE CURRENT DERATING CURVE

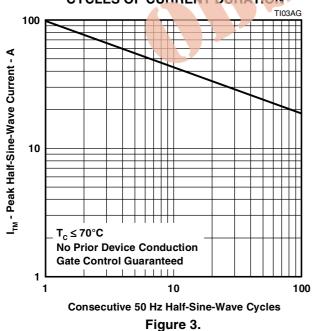


MAX ANODE POWER LOSS vs ON-STATE CURRENT



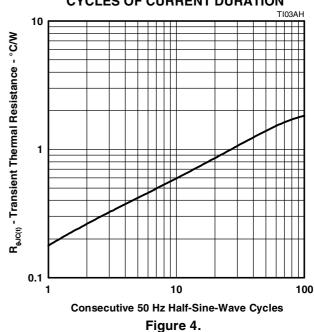
SURGE ON-STATE CURRENT

CYCLES OF CURRENT DURATION



TRANSIENT THERMAL RESISTANCE

CYCLES OF CURRENT DURATION

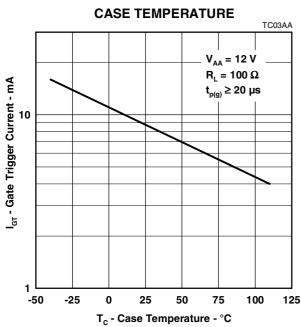


PRODUCT INFORMATION



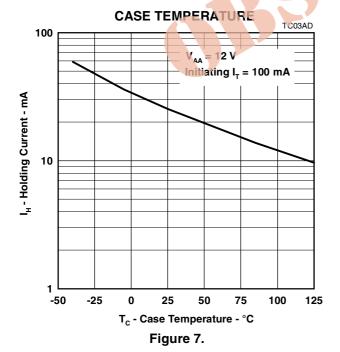
TYPICAL CHARACTERISTICS

GATE TRIGGER CURRENT vs

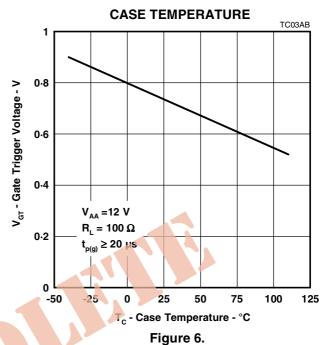


HOLDING CURRENT ٧S

Figure 5.

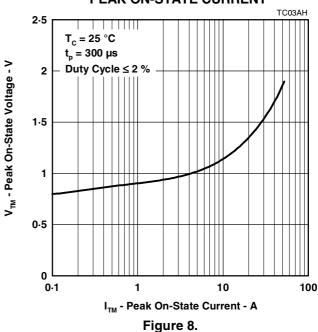


GATE TRIGGER VOLTAGE vs



PEAK ON-STATE VOLTAGE

PEAK ON-STATE CURRENT



PRODUCT INFORMATION